

OL-PCA9411

wafer level chip-scale package; 9 bumps; 1.24 x 1.24 x 0.525 mm (backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP9
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-9-2015

Table 1. Package summary

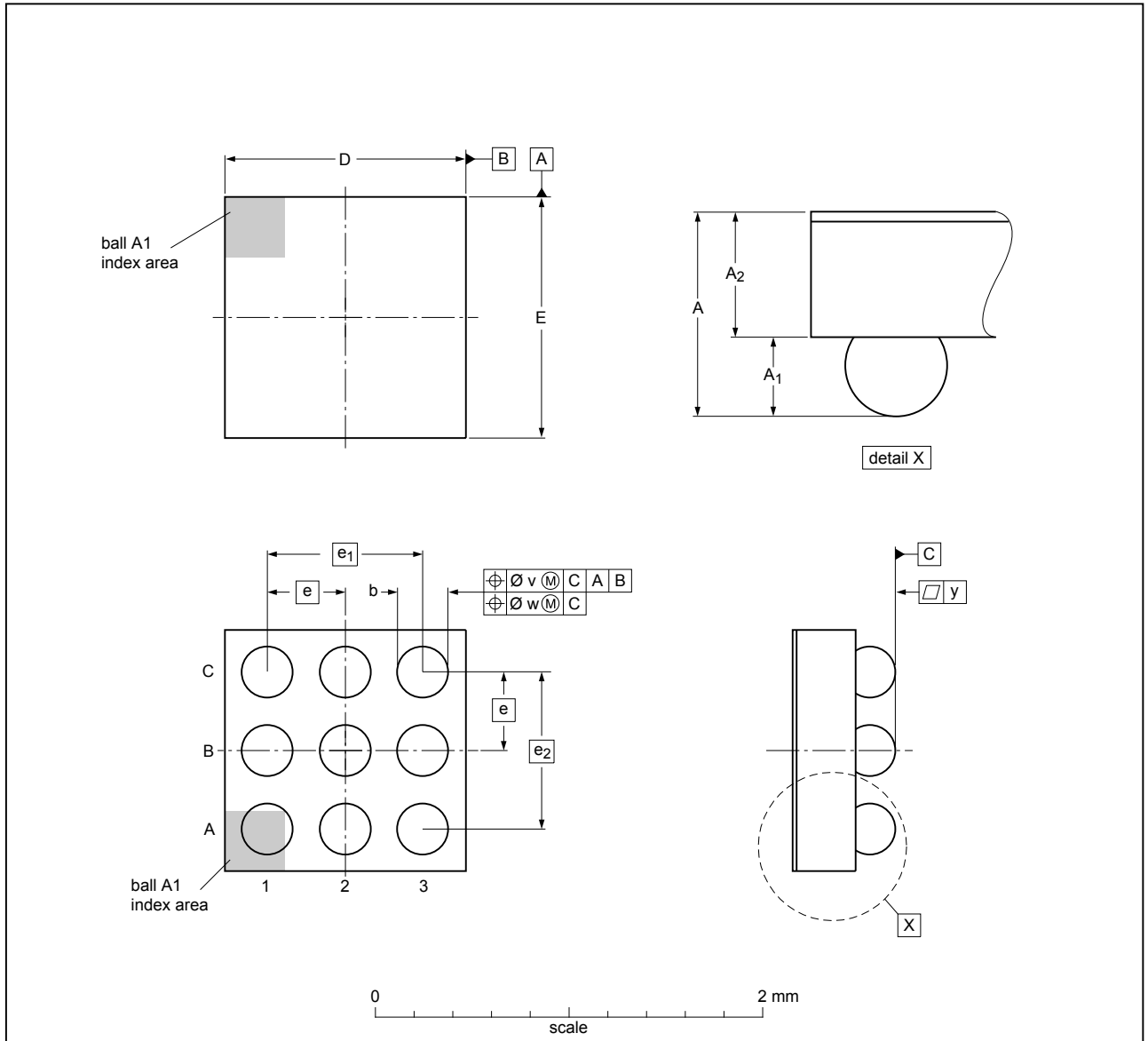
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.21	-	1.24	1.27	mm
E	package width	1.21	-	1.24	1.27	mm
A	seated height	0.485	-	0.525	0.565	mm
A ₂	package height	0.3	-	0.325	0.35	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	9	-	



wafer level chip-scale package; 9 bumps; 1.24 x 1.24 x 0.525 mm (backside coating included)

2. Package outline

WLCSP9: wafer level chip-scale package; 9 bumps; 1.24 x 1.24 x 0.525 mm (backside coating included) PCA9411



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.565	0.23	0.350	0.29	1.27	1.27						
nom	0.525	0.20	0.325	0.26	1.24	1.24	0.4	0.8	0.8	0.15	0.05	0.05
min	0.485	0.17	0.300	0.23	1.21	1.21						

Note: Backside coating 25 µm

wlcsp9_pca9411_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
PCA9411					-15-07-23- 15-09-29

Fig. 1. Package outline WLCSP9 (OL-PCA9411)

wafer level chip-scale package; 9 bumps; 1.24 x
1.24 x 0.525 mm (backside coating included)

3. Legal information

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